

ABSTRACT

A substrate processing vessel has a vessel body 100 and a cover 130 hermetically joined to the vessel body 100. The vessel body 100 is provided with a plurality of substrate support rods 102.

5 Each of the support rods 102 has a shank 103 and a head 104 having a diameter greater than that of the shank 103 and attached to the upper end of the shank 103. The shanks 103 penetrate the vessel body 100 and project downward from the vessel body 100.

10 When each substrate support rod 102 is lowered to its lower position, the head 104 is seated hermetically on a part, around the open upper end of a through hole 108 through which the shank 103 is inserted, of the vessel body 100. When each substrate support rod 102 is raised to its upper position, a space of a big thickness capable of receiving a wafer carrying arm 14a is formed

15 between the upper surface of the vessel body 100 and a wafer W supported on the substrate support rods 102. A processing space defined by the substrate processing vessel may be very thin, the amount of a processing fluid necessary for processing the wafer W can be reduced and throughput can be increased.

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